AMENDMENTS TO THE CLAIMS

Claim 1 (currently amended): A resin molded article obtained by performing a heat treatment to a resin composition comprising a liquid-crystalline polyester and an epoxy-group containing ethylene copolymer at a temperature lower than a flow-beginning temperature of said liquid-crystalline polyester, wherein the resin molded article has a smaller dielectric loss tangent than the resin molded article obtained from the resin composition without the heat treatment, and

wherein a content of said epoxy-group containing ethylene copolymer is in a range of 0.1 to 20 parts by weight with respect to 100 parts by weight of said liquid-crystalline polyester.

Claim 2 (original): The resin molded article as set forth in claim 1, wherein the dielectric loss tangent of the resin molded article is 90% or less of the dielectric loss tangent of the resin molded article obtained from the resin composition without the heat treatment.

Claim 3 (original): The resin molded article as set forth in claim 1, wherein the heat treatment is performed at a temperature between a lower limit temperature calculated by subtracting 120°C from the flow-beginning temperature of said liquid-crystalline polyester and an upper limit temperature calculated by subtracting 20°C from the flow-beginning temperature.

Claim 4 (canceled).

Claim 5 (original): The resin molded article as set forth in claim 1, wherein said epoxy-group containing ethylene copolymer contains 80 to 95 wt% of an ethylene unit and 5 to 15 wt% of at least one of an unsaturated-carboxylic acid glycidyl ester unit and an unsaturated glycidyl ether unit in the molecule thereof.

Claim 6 (original): The resin molded article as set forth in claim 1, wherein said liquid-crystalline polyester contains 30 to 80 mol% of a repeating unit derived from 2-hydroxy-6-naphthoic acid, 10 to 35 mol% of a repeating unit derived from an aromatic diol, and 10 to 35 mol% of a repeating unit derived from an aromatic dicarboxylic acid.

Claim 7 (Currently Amended): The resin molded article as set forth ~~froth~~ in claim 1 having a metal film formed in a circuit pattern thereon.

Claim 8 (currently amended): A method of producing a resin molded article comprising the steps of:

molding a resin composition comprising a liquid-crystalline polyester and an epoxy-group containing ethylene copolymer; and

performing a heat treatment to a resultant molded article at a temperature lower than a flow-beginning temperature of said liquid-crystalline polyester,

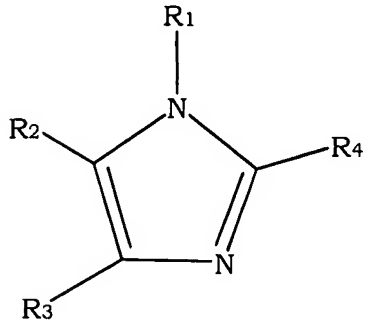
thereby obtaining the resin molded article having a smaller dielectric loss tangent than the resin molded article obtained from the resin composition without the heat treatment, and

wherein a content of said epoxy-group containing ethylene copolymer is in a range of 0.1 to 20 parts by weight with respect to 100 parts by weight of said liquid-crystalline polyester.

Claim 9 (original): The method as set forth in claim 8, wherein the heat treatment is performed at a temperature between a lower limit temperature calculated by subtracting 120°C from the flow-beginning temperature of said liquid-crystalline polyester and an upper limit temperature calculated by subtracting 20°C from the flow-beginning temperature.

Claim 10 (original): The method as set forth in claim 8, wherein said liquid-crystalline polyester is prepared by an ester-exchange and polycondensation reaction of at least one of an aromatic dicarboxylic acid and an aromatic hydroxycarboxylic acid, and an acylated compound prepared by acylating a phenolic hydroxyl group of at least one of an aromatic diol and an aromatic hydroxycarboxylic acid with a fatty acid anhydride

Claim 11 (original): The method as set forth in claim 10, wherein the ester-exchange and polycondensation reaction is performed in the presence of an imidazole compound represented by the following chemical formula:



wherein, each of "R_1" to "R_4" is selected from hydrogen atom, alkyl group having a carbon number of 1 to 4, hydroxymethyl group, cyano group, cyanoalkyl group having a carbon number of 1 to 4, cyanoalkoxy group having a carbon number of 1 to 4, carboxyl group, amino group, aminoalkyl group having a carbon number of 1 to 4, aminoalkoxy group having a carbon number of 1 to 4, phenyl group, benzyl group, phenylpropyl group, and a formyl group.

Claim 12 (New): The resin molded article of claim 1, wherein the resin molded article is a circuit board.

Claim 13 (New): A resin molded article produced by the method comprising the steps of:

molding a resin composition comprising a liquid-crystalline polyester and an epoxy-group containing ethylene copolymer; and

performing a heat treatment to a resultant molded article at a temperature lower than a flow-beginning temperature of said liquid-crystalline polyester,

thereby obtaining the resin molded article having a smaller dielectric loss tangent than the resin molded article obtained from the resin composition without the heat treatment, and

wherein a content of said epoxy-group containing ethylene copolymer is in a range of 0.1 to 20 parts by weight with respect to 100 parts by weight of said liquid-crystalline polyester.